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<table>
<tr><td rowspan="2">**Product Manual**</td><td>**Tuya BT3L-G BLE Module**</td></tr>
<tr><td>Version: 1.0.0   Date: 2019-10-24   No.: 0000000001</td></tr>
</table>

1   Product Overview

BT3L-G is an embedded Bluetooth Low Energy (BLE) module that Tuya has developed. It consists of a highly integrated Bluetooth chip (TLSR8250F512GT32) and several peripheral circuits, with an embedded Bluetooth network protocol stack and robust library functions. BT3L-G also contains a low-power 32-bit multipoint control unit (MCU), BLE 5.0 or 2.4 GHz radio, 4 MB flash memory, 48 KB static random-access memory (SRAM), and nine multiplexing I/O pins.

1.1   Features

✧   Embedded low-power 32-bit MCU, which can also function as an application processor

●   Clock rate: 48 MHz

✧   Working voltage: 1.8 V to 3.6 V (Under 1.8 V to 2.7 V, the module can start but the RF performance is not guaranteed. Under 2.8 V to 3.6 V, the module performance is normal.)

✧   Peripherals: nine pulse width modulation (PWM) pins

✧   BLE RF features

●   Compatible with BLE 5.0

●   Up to 2 Mbit/s RF data rate

●   TX power: +10 dBm

●   RX sensitivity: –94.5 dBm at BLE 1 Mbit/s

●   Embedded Advanced Encryption Standard (AES) hardware encryption

●   Onboard PCB antenna

●   Working temperature: –20°C to +105°C

1.2 Applications

✧ Smart LED lights

✧ Smart households

✧ Smart low-power sensors

Change History

No.	Date	Change Description	Version After Change
1	2019-10-24	This is the first release.	1.0.0

Contents

Figures

Tables

2 Module Interfaces

2.1 Dimensions and Footprint

BT3L-G has two rows of pins with a 2 mm pin spacing.

The BT3L-G dimensions (H x W x D) are 3.3±0.15 mm x 16±0.35 mm x 24±0.35 mm. The PCB thickness is 0.8±0.1 mm. Figure 2-1 shows the BT3L-G front and rear views.
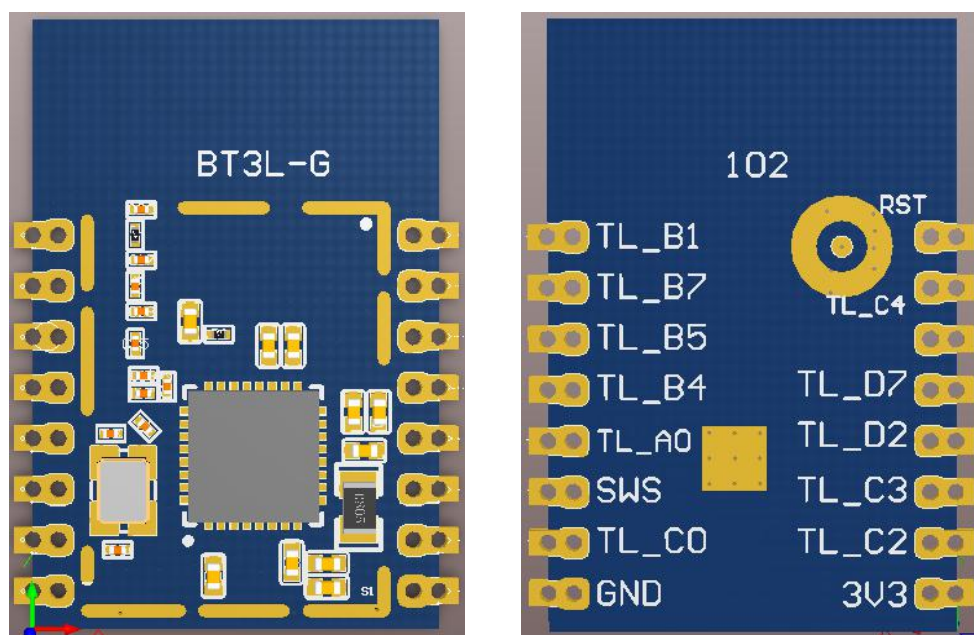
Figure 2-1 BT3L-G front and rear views

2.2 Interface Pin Definition

Table 2-1 BT3L-G interface pins

Pin No.	Symbol	I/O Type	Function
1	RST	I/O	Hardware reset pin, which is active at a low level and is connected to the RESETB pin on the internal IC
2	ADC	AI	12-bit ADC pin, which is connected to the TL_C4 pin on the internal IC

Pin No.	Symbol	I/O Type	Function
3	NC	I/O	NC
4	TL_D7	I/O	GPIO, which is connected to the TL_D7 pin on the internal IC
5	TL_D2	I/O	Common I/O pin, which can be used as a PWM output of the LED drive and is connected to the TL_D2 pin on the internal IC
6	TL_C3	I/O	Common I/O pin, which can be used as a PWM output of the LED drive and is connected to the TL_C3 pin on the internal IC
7	TL_C2	I/O	Common I/O pin, which can be used as a PWM output of the LED drive and is connected to the TL_C2 pin on the internal IC
8	VDD_BAT	P	Power supply pin (3.3 V)
9	GND	P	Power supply reference ground pin
10	TL_C0	I/O	GPIO, which is connected to the TL_C0 pin on the internal IC
11	SWS	Input	Programming pin, which is connected to the TL_D4 pin on the internal IC
12	TL_A0	I/O	GPIO, which is connected to the TL_A0 pin on the internal IC
13	TL_B4	I/O	Common I/O pin, which can be used as a PWM output of the LED drive and is connected to the TL_B4 pin on the internal IC
14	TL_B5	I/O	Common I/O pin, which can be used as a PWM output of the LED drive and is connected to the TL_B5 pin on the internal IC
15	TL_B7	I/O	Serial interface receiving pin (UART RX), which is connected to the TL_B7 pin on the internal IC
16	TL_B1	I/O	Serial interface transmission pin (UART TX), which is connected to the TL_B1 pin on the internal IC

Note:

1. **P** indicates power supply pins, **I/O** indicates input/output pins, and **AI** indicates analog input pins.

2. If you have special requirements for light colors controlled by PWM outputs, contact Tuya business personnel.

3 Electrical Parameters

3.1 Absolute Electrical Parameters

Table 3-1 Absolute electrical parameters

Parameter	Description	Minimum Value	Maximum Value	Unit
Ts	Storage temperature	–65	150	°C
VCC	Power supply voltage	–0.3	3.9	V
Static electricity voltage (human body model)	Tamb = 25°C	N/A	2	kV
Static electricity voltage (machine model)	Tamb = 25°C	N/A	0.5	kV

3.2 Electrical Conditions

Table 3-2 Normal electrical conditions

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
Ta	Working temperature	–40	N/A	105	°C
VCC	Working voltage	2.8	3.3	3.6	V
V_{IL}	I/O low-level input	VSS	N/A	VCC x 0.3	V
V_{IH}	I/O high-level input	VCC x 0.7	N/A	VCC	V
V_{OL}	I/O low-level output	VSS	N/A	VCC x 0.1	V
V_{OH}	I/O high-level output	VCC x 0.9	N/A	VCC	V

3.3 Power Consumption

Table 3-3 Power consumption in different working modes

Symbol	Description	Typical Value	Unit
I_{tx}	Constant transmission, 0 dBm output power	6.6	mA
I_{rx}	Constant receiving	6.3	mA
I_{DC}	Connected to a mesh network	7.3	mA
$I_{deepsleep1}$	Deep sleep mode 1 (16 KB RAM is reserved.)	1.2	µA
$I_{deepsleep2}$	Deep sleep mode 2 (No RAM is reserved.)	0.4	µA

4 RF Features

4.1 Basic RF Features

Table 4-1 Basic RF features

Parameter	Description
Frequency band	2.4 GHz ISM band
Wireless standard	BLE 4.2 or 5.0
Data transmission rate	1 Mbit/s or 2 Mbit/s
Antenna type	Onboard PCB antenna

4.2 RF TX Power

Table 4-2 Power during constant transmission

Parameter	Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power	–22	10	10.5	dBm
20 dB modulation signal bandwidth (1 Mbit/s)	N/A	2500	N/A	kHz
20 dB modulation signal bandwidth (2 Mbit/s)	N/A	1400	N/A	kHz

4.3 RF RX Sensitivity

Table 4-3 RX sensitivity

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
RX sensitivity	1 Mbit/s	N/A	–94.5	N/A	dBm
	2 Mbit/s	N/A	–91	N/A	
Frequency offset error	1 Mbit/s	–250	N/A	+300	kHz
	2 Mbit/s	–300	N/A	+200	
Co-channel interference suppression	N/A	N/A	–10	N/A	dB

5 Antenna Information

5.1 Antenna Type

BT3L-G uses an onboard PCB antenna.

5.2 Antenna Interference Reduction

To ensure optimal RF performance, it is recommended that the antenna be at least 15 mm away from other metal parts. If metal materials are wrapped around the antenna, the wireless signals will be reduced greatly, deteriorating the RF performance. As a dual in-line package (DIP), BT3L-G is through-hole mounted onto the PCB. Sufficient space needs to be reserved for the antenna.

6　Packaging Information and Production Instructions

6.1　Mechanical Dimensions and Rear Solder Pad Dimensions
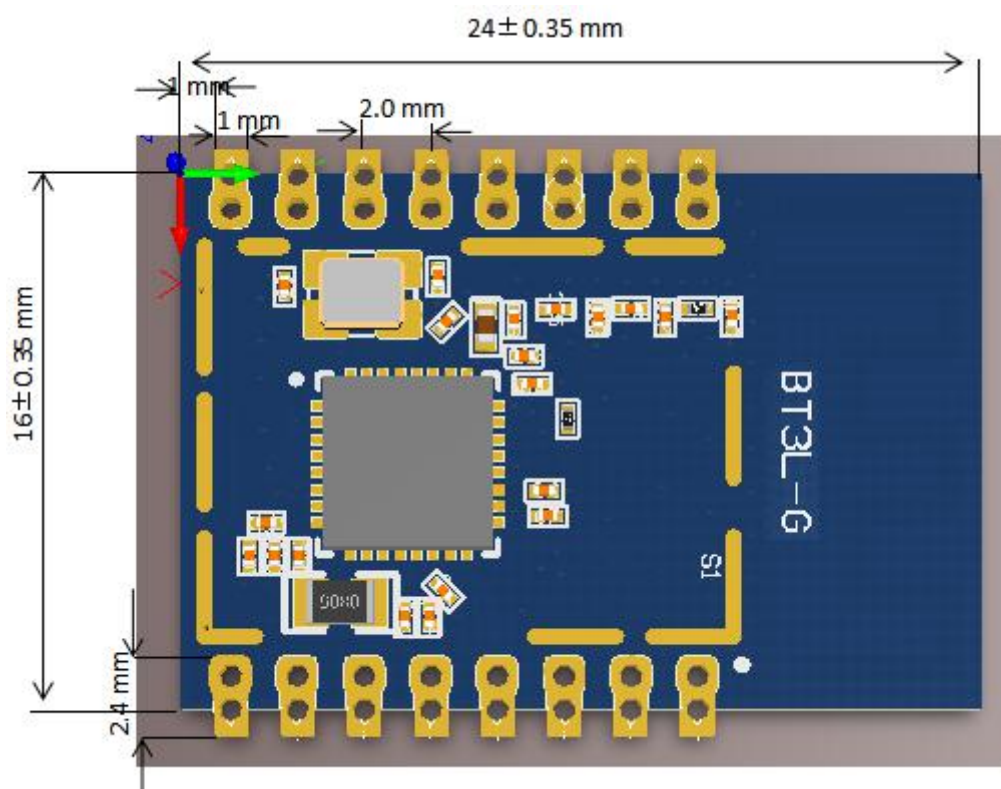

Figure 6-1 BT3L-G mechanical dimensions and rear solder pad dimensions

Note: The default dimensional tolerance is ±0.35 mm, and the tolerance for some measurements is ±0.1 mm. If a customer has other requirements, clearly specify them in the datasheet after communication.

6.2　Production Instructions

1.　Use an SMT placement machine to mount the stamp hole module that Tuya produces onto the PCB within 24 hours after the module is unpacked and the firmware is burned. If not, vacuum pack the module again. Bake the module before mounting it onto the PCB.

(1) SMT placement equipment

    i. Reflow soldering machine

    ii. Automated optical inspection (AOI) equipment

    iii. Nozzle with a 6 mm to 8 mm diameter

(2) Baking equipment

    i. Cabinet oven

    ii. Anti-static heat-resistant trays

    iii. Anti-static heat-resistant gloves

2. Storage conditions for a delivered module are as follows:

(1) The moisture-proof bag is placed in an environment where the temperature is below 30°C and the relative humidity is lower than 70%.

(2) The shelf life of a dry-packaged product is six months from the date when the product is packaged and sealed.
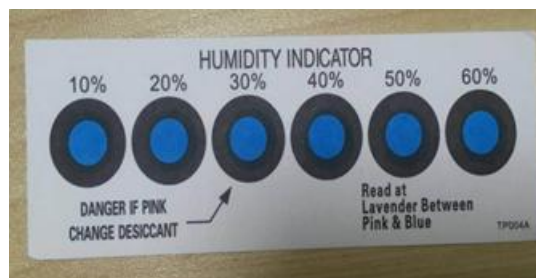
(3) The package contains a humidity indicator card (HIC).

Figure 6-2 HIC for BT3L-G

3. Bake a module based on HIC status as follows when you unpack the module package:

(1) If the 30%, 40%, and 50% circles are blue, bake the module for 2 consecutive hours.

(2) If the 30% circle is pink, bake the module for 4 consecutive hours.

(3) If the 30% and 40% circles are pink, bake the module for 6 consecutive hours.

(4) If the 30%, 40%, and 50% circles are pink, bake the module for 12 consecutive hours.

4. Baking settings:

    (1) Baking temperature: 125±5°C

    (2) Alarm temperature: 130°C

    (3) SMT placement ready temperature after natural cooling: < 36°C

    (4) Number of drying times: 1

    (5) Rebaking condition: The module is not soldered within 12 hours after baking.

5. Do not use SMT to process modules that have been unpacked for over three months. Electroless nickel immersion gold (ENIG) is used for the PCBs. If the solder pads are exposed to the air for over three months, they will be oxidized severely and dry joints or solder skips may occur. Tuya is not liable for such problems and consequences.

6. Before SMT placement, take electrostatic discharge (ESD) protective measures.

7. To reduce the reflow defect rate, draw 10% of the products for visual inspection and AOI before first SMT placement to determine a proper oven temperature and component placement method. Draw 5 to 10 modules every hour from subsequent batches for visual inspection and AOI.

6.3 Recommended Oven Temperature Curve

Perform SMT placement based on the following reflow oven temperature curve. The highest temperature is 245°C.

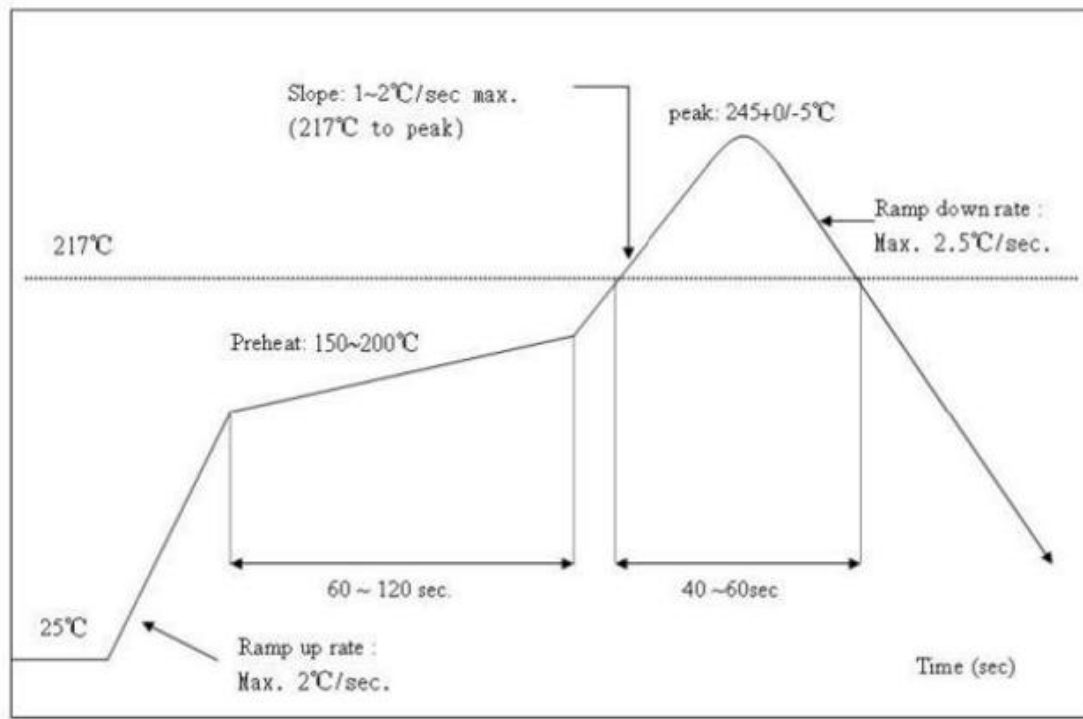Based on the IPC/JEDEC standard, perform reflow soldering on a module at most twice.

Figure 6-3 Oven temperature curve

6.4 Storage Conditions

CAUTION
This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL **3**

If Blank, see adjacent bar code label

1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)

2. Peak package body temperature: _____ 260 _____ °C
   If Blank, see adjacent bar code label

3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within: _____ 168 _____ hrs. of factory conditions
      If Blank, see adjacent bar code label
      ≤ 30°C/60%RH, OR
   b) Stored at <10% RH

4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is > 10% when read at 23 ± 5°C
   b) 3a or 3b not met.

5. If baking is required, devices may be baked for 48 hrs. at 125 ± 5°C

   Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: _____
   If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

7 MOQ and Packing Information

MOQ and packing information				
Product Model	MOQ	Packing Method	Number of Modules in Each Reel Pack	Number of Reel Packs in Each Box
BT3L-G	3600	Carrier tape and reel packing	900	4

8 Appendix: Statement

Federal Communications Commission (FCC) Declaration of Conformity

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules.

Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

15.105 Information to the user.

(b) For a Class B digital device or peripheral, the instructions furnished the user shall include the following or similar statement, placed in a prominent location in the text of the manual:

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules.

These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful

interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

—Reorient or relocate the receiving antenna.

—Increase the separation between the equipment and receiver.

—Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.

—Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator and your body.

Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

The availability of some specific channels and/or operational frequency bands are country dependent and are firmware programmed at the factory to match the intended destination.

The firmware setting is not accessible by the end user.

The final end product must be label led in a visible area with the following:

"Contains Transmitter Module FCC ID:2ANDL-BT3L-G"

This radio module must not installed to co-locate and operating simultaneously with other radios in host system, additional testing and equipment authorization may be required to operating simultaneously with other radio.

Declaration of Conformity European notice

Hereby, Hangzhou Tuya Information Technology Co., Ltd declares that this Bluetooth module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EU. A copy of the Declaration of conformity can be found at https://www.tuya.com.